

Title (en)

Thick film conductor compositions for use with an aluminum nitride substrate.

Title (de)

Dickfilm-Leiterzusammensetzungen zur Verwendung mit einem Aluminiumnitrid-Substrat.

Title (fr)

Compositions conductrices en couche épaisse pour utilisation avec un substrat de nitrure d'aluminium.

Publication

EP 0306270 A1 19890308 (EN)

Application

EP 88308022 A 19880830

Priority

US 9108187 A 19870831

Abstract (en)

A thick film conductor composition adapted to be bonded to an aluminum nitride substrate is provided which comprises a sufficient amount of conductive metallic material to render the conductor composition electrically conductive when bonded to the substrate, a glass frit binder for the metallic material capable of being bonded to the substrate, and a lithium containing compound capable of reacting with the substrate upon heating so as to aid in adherently bonding the conductor composition to the aluminum nitride substrate. A thick film conductor bonded onto the surface of an aluminum nitride substrate as well as a method of producing the same are also provided.

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H01B 1/16; **H01L 49/02**

IPC 8 full level

H05K 1/09 (2006.01); **C03C 3/066** (2006.01); **C03C 3/091** (2006.01); **C04B 41/88** (2006.01); **H01B 1/16** (2006.01)

CPC (source: EP US)

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Citation (search report)

- GB 1251766 A 19711027
- US 4540673 A 19850910 - TAKEDA YUKIO [JP], et al
- EP 0153737 A2 19850904 - TOSHIBA KK [JP]
- EP 0132810 A1 19850213 - DU PONT [US]

Cited by

GB2285264B; US9117567B2; WO2011120060A3

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